



- (51) International Patent Classification:
B23B 27/06 (2006.01) *G06F 3/041* (2006.01)
B32B 7/02 (2006.01)
- (21) International Application Number:
PCT/US2014/068993
- (22) International Filing Date:
8 December 2014 (08.12.2014)
- (25) Filing Language: English
- (26) Publication Language: English
- (30) Priority Data:
61/913,513 9 December 2013 (09.12.2013) US
- (71) Applicant: **3M INNOVATIVE PROPERTIES COMPANY** [US/US]; 3M Center, Post Office Box 33427, Saint Paul, Minnesota 55133-3427 (US).
- (72) Inventors: **CHEN, Wan-Chun**; 6F, No. 95 Dunhua S. Road, Sec. 2, Taipei, 10682 (TW). **CHIU, Chun-Ming**; 6F, No. 95 Dunhua S. Road, Sec. 2, Taipei, 10682 (TW). **LUO, Hui**; 3M Center, Post Office Box 33427, Saint Paul, Minnesota 55133-3427 (US). **WANG, Tze Yuan**; 6F, No. 95 Dunhua S. Road, Sec. 2, Taipei, 10682 (TW). **YU, Ta-hua**; 3M Center, Post Office Box 33427, Saint Paul, Minnesota 55133-3427 (US).

- (74) Agents: **WOOD, Kenneth B.** et al.; 3M Center, Post Office Box 33427, Saint Paul, Minnesota 55133-3427 (US).
- (81) Designated States (*unless otherwise indicated, for every kind of national protection available*): AE, AG, AL, AM, AO, AT, AU, AZ, BA, BB, BG, BH, BN, BR, BW, BY, BZ, CA, CH, CL, CN, CO, CR, CU, CZ, DE, DK, DM, DO, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, GT, HN, HR, HU, ID, IL, IN, IR, IS, JP, KE, KG, KN, KP, KR, KZ, LA, LC, LK, LR, LS, LU, LY, MA, MD, ME, MG, MK, MN, MW, MX, MY, MZ, NA, NG, NI, NO, NZ, OM, PA, PE, PG, PH, PL, PT, QA, RO, RS, RU, RW, SA, SC, SD, SE, SG, SK, SL, SM, ST, SV, SY, TH, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, ZA, ZM, ZW.
- (84) Designated States (*unless otherwise indicated, for every kind of regional protection available*): ARIPO (BW, GH, GM, KE, LR, LS, MW, MZ, NA, RW, SD, SL, ST, SZ, TZ, UG, ZM, ZW), Eurasian (AM, AZ, BY, KG, KZ, RU, TJ, TM), European (AL, AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HR, HU, IE, IS, IT, LT, LU, LV, MC, MK, MT, NL, NO, PL, PT, RO, RS, SE, SI, SK, SM, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, KM, ML, MR, NE, SN, TD, TG).

Published:

— with international search report (Art. 21(3))

(54) Title: TRANSPARENT CONDUCTIVE MULTILAYER ASSEMBLY

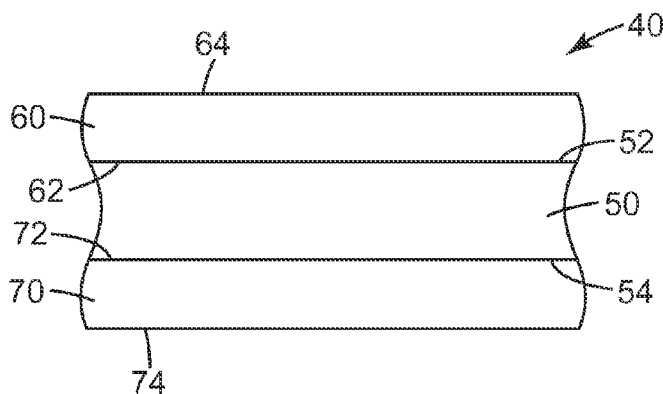


Fig. 1

(57) Abstract: A transparent multilayer assembly, including a transparent organic polymeric flexible substrate, a transparent conductive layer on the first major surface of the substrate and an antireflective layer on the second major surface of the substrate.